AMENDMENTS TO THE CLAIMS

This listing of claims replaces all prior versions, and listing, of claims in the specification:

- 1. (Currently amended) A circuit coupled to an output device, the circuit comprising at least one transistor device comprising at least one p-channel device, said at least one transistor device adapted to limit a duration of a high voltage across the output device thereby reducing hot carrier injection stress across the output device.
- 2. (Original) The circuit of Claim 1, further comprising two stacked transistor devices coupled to the output device.
- 3. (Currently Amended) The circuit of Claim 1, wherein said at least one p-channel device is transistors coupled to the output device.
- 4. (Currently Amended) The circuit of Claim <u>2</u> 1, wherein said <u>two stacked</u> transistor <u>device comprises</u> <u>devices comprise</u> two stacked p-channel <u>transistors devices</u> coupled to the output device.
- 5. (Original) The circuit of Claim 1, wherein the output device comprises at least one n-channel output transistor.
- 6. (Currently Amended) The circuit of Claim 1, wherein the output device comprises two stacked n-channel <u>output</u> transistors.
 - 7-8. (Cancelled)
 - 9. (Currently amended) An integrated circuit comprising:

an IO PAD;

an output circuit coupled to at least said IO PAD; and

a stress circuit comprising at least one p-channel transistor, said stress circuit coupled to at least said output circuit and said IO PAD and adapted to limit a duration of

a high voltage across said output circuit when said output circuit is enabled, thereby reducing stress on said output circuit.

10-11. (Cancelled)

10-11. (Cancelled)

- 12. (Previously presented) The integrated circuit of Claim 9, wherein said at least one p-channel transistor comprises two stacked p-channel transistors.
- 13. (Currently Amended) The integrated circuit of Claim 9, wherein said output circuit comprises at least one <u>output</u> transistor.
- 14. (Currently Amended) The integrated circuit of Claim 13, wherein said <u>at least</u> one output transistor comprises an n-channel transistor.
- 15. (Currently Amended) The integrated circuit of Claim 13, wherein said <u>at least</u> one output transistor comprises two stacked n-channel transistors.
- 16. (Currently Amended) A method of controlling hot carrier injection stress comprising limiting a duration of a high voltage across an output device using a stress circuit comprising at least one two p-channel transistor transistors to limit said duration of said high voltage across said output device when said output device is enabled.

17. (Cancelled)

18. (Previously Presented) A method of reducing stress across an output circuit, comprising:

determining if the output circuit is tri-stated;

determining if a PAD voltage is greater than a predetermined voltage level; enabling the output circuit;

turning on a stress circuit comprising at least one p-channel transistor, dissipating a voltage across the output circuit; and

preventing the output circuit from experiencing HCl stress.

19-21. (Cancelled)

- 22. (New) The method of Claim 18, wherein said at least one p-channel transistor is coupled to the output circuit.
- 23. (New) The method of Claim 18, wherein said stress circuit comprises two stacked p-channel transistors coupled to the output circuit.
- 24. (New) The method of Claim 18, wherein the output circuit comprises at least one n-channel output transistor.
- 25. (New) The method of Claim 18, wherein the output circuit comprises two stacked n-channel output transistors.
- 26. (New) An HCI stress circuit coupled to both an output circuit and an IO pad, the HCI stress circuit consisting of two stacked p-channel transistor devices, said two stacked p-channel transistor devices adapted to limit a duration of a high voltage across the output circuit thereby reducing hot carrier injection stress across the output circuit.
- 27. (New) The HCI stress circuit of Claim 26, wherein at least one of said two stacked p-channel transistor devices is coupled to the output circuit.

- 28. (New) The HCI stress circuit of Claim 26, wherein the output device comprises at least one n-channel output transistor circuit.
- 29. (New) The HCI stress circuit of Claim 26, wherein the output device comprises two stacked n-channel output transistor circuit.

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